

IEEE 802.3cg 10SPE TF/802.3 10BPE SG AdHoc meeting January 03 2018

Prepared by Peter Jones

Proposed Agenda:

1. Agenda/Admin Peter Jones

Presentations posted at:

<http://www.ieee802.org/3/cg/public/adhoc/index.html>

Agenda/Admin Peter Jones:

Meeting began at 7:05am PT.

1. Reviewed the Attendance information related to the ad hoc(s).
2. Displayed pre & post-par slide deck, reviewed patent policy, participation conditions.
<https://development.standards.ieee.org/myproject/Public/mytools/mob/preparslides.pdf> (10BP)
<https://development.standards.ieee.org/myproject/Public/mytools/mob/slideset.ppt> (10SPE)
<https://mentor.ieee.org/802-ec/dcn/17/ec-17-0093-05-OPNP-ieee-802-participation-slide-ppt.ppt>
3. Made potentially essential patents call for 802.3cg – 10SPE
No-one responded.
4. Reminded participants to indicate full names and employer/affiliations correctly for the meeting minutes.
5. Did not ask for approval of December 20 minutes

Presentations/Discussion.

Start and Administrivia

- Note new PATCOM slide set published and incorporated for "post-par" work -par (i.e., 802.3cg)

BPE Chair's Comments Jon Lewis

- Making good progress.
- Discussed plan for Geneva.
- 10BPE SG Goals for Geneva – get agreement on proposed changes to 802.3cg PAR, CSD, Objectives. PAD & CSD need to be pre-circulated before March meeting.
- Share time/room with 802.3cg 10SPE.

SPE Chair's Comments George Zimmerman

- Making good progress.
- TF review Ballot

- TF review ballot closes Sunday Jan 7th 23:59 AOE (see <http://www.ieee802.org/3/ballots/announce.html>).
- Please review announcement message (<http://www.ieee802.org/3/cg/email/msg00287.html>) for more information and guidance.
- Geneva interim
 - Timing in Geneva, times for arrival/departure fixed, time will be carefully managed.
 - Presentation requests and files – review <http://www.ieee802.org/3/cg/public/presentproc.html> . This means requests by Monday 15 January, files by Thursday 18 January.

Proposed PAR, CSDs and Objectives Changes

Peter Jones **Cisco**
George Zimmerman **CME(*)**

- Slides presented and discussed.
- Notes recorded on slides during meeting – update to be posted.
- Changes/issues/concerns to be discussed on & off the reflector before the next AdHoc meeting Jan 17th.

Definition and measurement of links in ISO/IEC

Dieter Schicketanz **consultant Reutlingen University**

- General: In all cases, make it clear whether references are to the current published ISO 11801-1:2017 specification, or to the draft of the specification in process in ISO/IEC JTC1 SC25 WG3.
- Page 3
 - It is copper not cooper
- Page 5
 - correct text about TCL/ELTCL
- Page 6
 - Make it clear that "not real" means complex impedance and transmitters are defined with "resistive" 100 Ohm
- Page 10
 - Make it clear that no changes are expected to cg limit definition and ISO would apply measurement and definition to the limits as appropriate.
 - Should we include page 10 notion in cg link clause? No, because no direct reference is possible.
 - Subject to these two points, and the general comment about references, no opposition to page 10 proposal.

Meeting closed – ~8:30 PT

Attendees (from Webex + emails)

Name	Employer	Affiliation	Attended 01/03
Amrik Bains	Cisco	Cisco	y
Aniruddha Phatak	Renesas	Renesas	y
Bob Voss	Panduit	Panduit	y
Brett McClellan	Marvell	Marvell	y
Brian Franchuck	Emerson	Emerson	y
Chad Jones	Cisco	Cisco	y
Chris Diminico	MC Communications/Panduit	MC Communications/Panduit	y
Conrad Zerna	Fraunhofer IIS	Fraunhofer IIS	y
Craig Gunther	Harmen	Harmen	y
Dale Borgeson	ED Engineering	Emerson	y
Dave Hess	CordData	CordData	y
David Brandt	Rockwell Automation	Rockwell Automation	y
David Law	HPE	HPE	y
David Malicoat	Independent	Independent	y
Dayin Xu	Rockwell Automation	Rockwell Automation	y
Dieter Schicketanz	Consultant, Reutlingen University	Consultant, Reutlingen University	y
Eric DiBiaso	TE	TE	y
Fatma Caliskan	Microchip	Microchip	y
Gary Irwin	CommScope	CommScope	y
Geoff Thompson	GraCaSI S.A.	Independent	y
George Zimmerman	CME Consulting	ADI, Aquantia, BMW, Cisco, Commscope	y
Gergely Huszak	Kone	Kone	y
Harald Zweck	Infineon	Infineon	y
Henry Muyschondt	Microchip	Microchip	y
James Withey	Fluke	Fluke	y
Jay Cordaro	Broadcom	Broadcom	y
Jens Gottron	Siemens	Siemens	y
Jim Bauer	Marvell	Marvell	y
Jon Lewis	Dell	Dell	y
Larry Matola	Delphi	Delphi	y
Laura Schweitz	Turck	Turck	y
Mario Traeber	Intel	Intel	y
Mark Bohm	Microchip	Microchip	y
Masood Shariff	CommScope	CommScope	y
Natalie Wienckowski	GE	GE	y
Nicola Scantamburlo	Canova Tech	Canova Tech	y

Paul Vanderlaan	Berk-Tek	Berk-Tek	y
Peter Jones	Cisco	Cisco	y
Phillip Brownele	TDK	TDK	y
Phong Pham	US Conec	US Conec	y
Piergiorgio Beruto	Canova Tech	Canova Tech	y
Steffen Graber	Pepperl+Fuchs	Pepperl+Fuchs	y
Tim Baggett	Microchip	Microchip	y
Valerie Maguire	Siemon	Siemon	y
Victor Berglund	MicroSemi	MicroSemi	y
Attendee count			45